**Features**
- Single Biasing Voltage (Self Biased)
- Frequency: 5-50GHz
- Gain: 11dB
- Noise Figure: 2.7~4.3dB
- Input /Output Return Loss:>14dB/>14dB
- P1dB: 9~12dBm
- IP3: 22dBm
- Power Supply: +5 V@43 mA
- Die Size: 1.54 x 1.38 x 0.1 mm

**Typical Applications**
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

**Electrical Specifications**

**TA = +25°C, Vd = +5V**

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Outline Drawing:
All Dimensions in μm

Assembly Drawing

Notes:
1. Die thickness: 100um
2. Typical bond pad is 100*100 μm²
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads
7. Input and output has DC Block.
8. Input/Output use two 25um gold wire, length less than 250um is recommended.

Maximum Ratings:
1. Control voltage: +9V
2. Input power: +23dBm
3. Operating temperature: -55°C to +125°C
4. Storage temperature: -65°C to +150°C